



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-10-31
Company Unique ID	NL 008751171801		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	A6WL*UN36AA6	A	64BA	2018-10-31
Amount	UoM	Unit type	ST ECOPACK Grade	
82.40	mg	Each	ECOPACK1	
	Comment	ECOPACK® or ECOPACK® 1 is STMicroelectronics trade name for ROHS compliant devices		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	3.9-4.9-1.35	12	gull wing	
Comment	Package: PowerSSO 12 monoframe. MDF valid for CPs: L5300GJTR and L5300GJ			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.01	Die	170
Lead	2.17	Soft solder	26335
Antimony trioxide	0.54	Mold compound	6553

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	2.17	Soft solder	26335
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	2.17	Soft solder	954685

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	A6WL*UN36AA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	2.978	mg	supplier	die	Silicon (Si)	7440-21-3		2.838	mg	952989	34442
				supplier	metallization	Aluminium (Al)	7429-90-5		0.019	mg	6380	231
				supplier	metallization	Tungsten (W)	7440-33-7		0.030	mg	10074	364
				supplier	Passivation	Silicon Nitride	12033-89-5		0.005	mg	1678	61
				supplier	Passivation	Silicon Oxide	7631-86-9		0.044	mg	14775	534
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.002	mg	672	24
				supplier	back side metallization	Gold (Au)	7440-57-5		0.004	mg	1343	49
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.014	mg	4701	170
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.022	mg	7388	267
				Leadframe	M-004 Copper and its alloys	31.052	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron (Fe)	7439-89-6						0.030	mg	966	364
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.009	mg	290	108
supplier	metallization	Silver (Ag)	7440-22-4						1.100	mg	35424	13350
Soft solder	Solder	2.273	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	2.170	mg	954685	26335
				supplier	solder	Silver (Ag)	7440-22-4		0.057	mg	25077	692
				supplier	solder	Tin (Sn)	7440-31-5		0.046	mg	20238	558
Bonding wires	M-011 Other inorganic materials	0.268	mg	supplier	wire	Gold (Au)	7440-57-5		0.268	mg	1000000	3252
				supplier	wire	Silver (Ag)	7440-22-4		0.000	mg	0	0
Encapsulation	M-015 Other organic materials	44.834	mg	supplier	mold compound	Silica, vitreous	60676-86-0		36.899	mg	823014	447803
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		3.138	mg	69992	38083
				supplier	mold compound	Phenol resin	9003-35-4		1.793	mg	39992	21760
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		1.345	mg	30000	16323
				supplier	mold compound	Antimony Trioxide	1309-64-4		0.538	mg	12000	6529
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		0.897	mg	20007	10886
				supplier	mold compound	Carbon black	1333-86-4		0.224	mg	4995	2718
				supplier	mold compound	Carbon black	1333-86-4		0.224	mg	4995	2718
Connections coating	Solder	0.995	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.995	mg	1000000	12075